

REMARKS

Pending Claims

Claims 1, and 3-12 are pending. Claims 1, 3, 4, 6, 7, 8, 10 and 12 have been amended. Claim 2 has been canceled without prejudice or disclaimer. No new matter has been added.

Specification

The Specification has been amended to enhance the clarity of the disclosure. A Substitute Specification, including marked-up and clean copies is attached. No new matter has been added. Support for the amendments to the specification are provided by the application as originally filed.

Claim Objections

Claim 1 has been amended to overcome the objection. Accordingly, the objection should be withdrawn.

Claim Rejections Under 35 U.S.C. §112

Claims 1-5 are rejected under 35 U.S.C. §112, second paragraph, as being indefinite for failing to particularly point out and distinctly claim the invention.

Applicants have amended claim 1 to clarify that the second principal surface, which is opposite the first principal surface, is exposed, as correctly interpreted by the Examiner in the examination of the present application. Further, claim 2 has been canceled thereby rendering

the rejection of claim 2 moot. Accordingly, the rejection under 35 U.S.C. §112, second paragraph, should be withdrawn.

Claim Rejections Under 35 U.S.C. §102

Claims 1-5 are rejected under 35 U.S.C. §102(b), as being anticipated by Suh et al, U.S. Patent No. 6,280,580. Applicants request reconsideration of the rejection in view of the foregoing amendments and for the following reasons.

The invention is directed to a thin film forming method and a thin film forming apparatus which makes it possible to form thin films simultaneously on both sides of a substrate, i.e., the first principal surface and the second principal surface on the side of the substrate opposite to the first principal surface. As shown in Fig. 1 and discussed in the Specification, for example, a guide 4 has a parallel portion 4A and an inclined portion 4B to increase the density of the particulate material forming the thin films by converging the particular thin film material 2A in the process of introducing the particulate thin film material 2A to the respective principal surfaces 1A and 1B of the substrate 1. See page 19, line 22 – page 20, line 6 of the Specification, for example. In this manner, the density of the thin film material on the first and second principal surfaces of the substrate is increased which enables efficient formation of the thin films. See the original Specification, page 21, lines 21-24, for example.

Suh is relied upon for disclosing the manufacturing of a double-sided high-temperature superconducting oxide thin film on substrate 6 in a thin film deposition chamber 11. Sputtering targets 1 and 2 are arranged on opposite sides of the substrate 6. However, Suh does not disclose exposing first and second principal surfaces of a substrate, and introducing particulate material including converging the particulate material and increasing

its density in the introducing of the particulate material on the first and second principal surfaces of the substrate. Suh discloses substrate heaters 3 and 4 and also separators 9 and 10 located on the centerline of the substrate. However, the reference does not disclose any structure for introducing and converging the particulate material to the substrate surfaces and increasing the density of the particulate material during the introducing as claimed by applicants.

Claims 3-5, which depend from claim 1, and claims 8-12, which depend from claim 6, are patentable over Suh, at least for being dependent from a base claim asserted to be allowable for the foregoing reasons. Accordingly, the rejection under 35 U.S.C. §102(b) should be withdrawn.

Conclusion

In view of the foregoing, Applicant respectfully requests that a timely Notice of Allowance be issued in this case.

Respectfully submitted,

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Date: October 12, 2010